

What is claimed is:

1. A semiconductor package comprising:

a carrier;

a plurality of first spacers disposed on the carrier;

6 a first chip disposed on the first spacers and defining an active surface and a back surface;

a plurality of contacts disposed on the carrier for being electrically connected to an external circuit;

a plurality of first bonding wires for electrically connecting the first chip to the contacts; and

12 an encapsulant encapsulating the first spacers, the active surface and the back surface of the first chip, and the first bonding wires.

2. The semiconductor package as claimed in claim 1, further comprising a plurality of solder balls disposed on the carrier and electrically connected to the contacts for being electrically connected to the external circuit.

3. The semiconductor package as claimed in claim 1, wherein the carrier is a substrate.

18 4. The semiconductor package as claimed in claim 1, wherein the carrier is a lead frame having a die pad on which the first spacers are disposed.

5. The semiconductor package as claimed in claim 4, wherein the lead frame further comprises a plurality of inner leads for being electrically connected to the first chip and a plurality of outer leads electrically connected to the inner leads for being electrically connected to the external circuit.

24 6. The semiconductor package as claimed in claim 1, further comprising:

a plurality of second spacers disposed on the first chip;

a second chip disposed on the second spacers; and

a plurality of second bonding wires for electrically connecting the second chip to the contacts,

wherein the encapsulant further encapsulates the second spacers, the second chip, and the second bonding wires.

7. The semiconductor package as claimed in claim 1, further comprising a plurality of adhesives mixed with the spacers and disposed on the carrier.

8. A semiconductor package comprising:

- 6 a first chip;
- a plurality of first spacers supporting the first chip;
- a plurality of contacts for being electrically connected to an external circuit;
- a plurality of first bonding wires for electrically connecting the first chip to the contacts;

12 an encapsulant encapsulating the first spacers, the first chip, and the first bonding wires.

9. The semiconductor package as claimed in claim 8, further comprising:

- a plurality of second spacers disposed on the first chip;
- a second chip disposed on the second spacers; and
- a plurality of second bonding wires for electrically connecting the second chip to the contacts,

18 wherein the encapsulant further encapsulates the second spacers, the second chip, and the second bonding wires.

10. The semiconductor package as claimed in claim 8, further comprising a plurality of adhesives mixed with the spacers.

11. A semiconductor package comprising:

- a substrate
- 24 a first chip defining an active surface and having bumps disposed on the active surface for being connected to the substrate;
- a plurality of spacers disposed on the first chip;
- a second chip disposed on the spacers;

a plurality of contacts disposed on the substrate for being electrically connected to an external circuit;

a plurality of bonding wires for electrically connecting the second chip to the contacts;

6 an encapsulant encapsulating the spacers, the first chip, the second chip and the bonding wires.

12. The semiconductor package as claimed in claim 11, further comprising a plurality of solder balls disposed on the substrate and electrically connected to the contacts for being electrically connected to the external circuit.

13. The semiconductor package as claimed in claim 11, further comprising a plurality of adhesives mixed with the spacers.

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